



Materials Declaration

Package	CSP BGA
Body Size	10 X 10
Ball Count	144
Option	SnPbAg
Ball Size	0.45

Molding Compound				
Item	% of Compound	Weight (g)	PPM	
SiO2 Filler	90	8.87 E-02	291134	
Epoxy Resin	4.8	4.73 E-03	15527	
Phenol Resin	3.91	3.85 E-03	12648	
Sb2O3	0.69	6.80 E-04	2232	
Bromine	0.6	5.91 E-04	1941	

Laminate				
Item	% of Laminate	Weight (g)	PPM	
BT-Epoxy	28	3.32 E-02	108997	
Glass Fiber	25	2.96 E-02	97319	
Copper	19	2.25 E-02	73963	
Gold	11	1.30 E-02	42820	
Nickel	7.8	9.25 E-03	30364	
Solder Mask	9.35	1.11 E-02	36397	
Brominated Compound	Confidential Not Determined			

Solder Ball				
Item	% of Solder Ball	Weight (g)	PPM	
Sn	62	3.58 E-02	117528	
Pb	36	2.08 E-02	68242	
Ag	2	1.15 E-03	3791	

Bond Wires				
Item	% of Wire	Weight (g)	PPM	
Au	99.99	8.33 E-04	2736	

Chip				
Item	% of Chip	Weight (g)	PPM	
Si	100	2.50 E-02	82245	

Die Attach				
Item	% of Die Attach	Weight (g)	PPM	
Resin	23	8.49 E-04	2787	
Ag Filler	77	2.84 E-03	9329	

Molding Compound		
Item	PPM	Method
Cd	<5	BS EN 1122:2001B (ICPaes)

Die Attach Paste		
Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	ICP-AES

Laminate		
Item	PPM	Method
Pb	<14	
Cd	<2.0	
Hg	<2.0	
Cr+6	<19	
PBB	Not Detected	
PBDE	Not Detected	

Package Totals		
Weight (g)	PPM	
3.05 E-01	1000000	

STS-BC-B

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

8/9/04

